Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic				Symbol	Value	Units
Drain-Source Voltage				V_{DSS}	20	V
Gate-Source Voltage				V_{GSS}	±12	V
Continuous Drain Current (Note 5)	V_{GS} = 10V	Steady State	T_A = +25°C T_A = +70°C	I_D	5.4 4.3	A
Continuous Drain Current (Note 5)	V_{GS} = 2.5V	Steady State	T_A = +25°C T_A = +70°C	I_D	4.6 3.7	A
Continuous Body Diode Forward Current (Note 5)		Steady Stat	T_A = +25°C	I_S	0.9	A
Pulsed Drain Current (Note 5) 10µs pulse, duty cycle = 1%				I_{DM}	30	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_D	0.78	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	161	°C/W
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	26	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	-	-	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	-	-	1.0	µA	V_{DS} = 20V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	-	-	10	µA	V_{GS} = ±10V, V_{DS} = 0V
Gate-Source Breakdown Voltage	BV_{SGS}	±12	-	-	V	V_{DS} = 0V, I_G = ±250µA
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(th)}$	0.35	-	0.95	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS\ (ON)}$	-	15.5	18.5	mΩ	V_{GS} = 10V, I_D = 7A
		-	16.5	21		V_{GS} = 4.5V, I_D = 7A
		-	17	21.5		V_{GS} = 4.0V, I_D = 7A
		-	17.5	22.5		V_{GS} = 3.6V, I_D = 6.5A
		-	18	23		V_{GS} = 3.1V, I_D = 6.5A
		-	19	24		V_{GS} = 2.5V, I_D = 5.5A
		-	24	31		V_{GS} = 1.8V, I_D = 3.5A
Forward Transfer Admittance	$\|Y_{fs}\|$	-	13	-	S	V_{DS} = 5V, I_D = 5A
Diode Forward Voltage	V_{SD}	-	0.7	1.0	V	V_{GS} = 0V, I_S = 1A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C_{iss}	-	143	-	pF	V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	-	74	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	29	-	pF	
Gate Resistance	R_g	-	202	-	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge	Q_g	-	8.8	-	nC	V_{GS} = 4.5V, V_{DS} = 10V, I_D = 6.5A
Gate-Source Charge	Q_{gs}	-	1.4	-	nC	
Gate-Drain Charge	Q_{gd}	-	3.0	-	nC	
Turn-On Delay Time	$t_{D(on)}$	-	53	-	ns	V_{DD} = 10V, V_{GS} = 4.5V, R_L = 10Ω, R_G = 6Ω
Turn-On Rise Time	t_r	-	78	-	ns	
Turn-Off Delay Time	$t_{D(off)}$	-	562	-	ns	
Turn-Off Fall Time	t_f	-	234	-	ns	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.

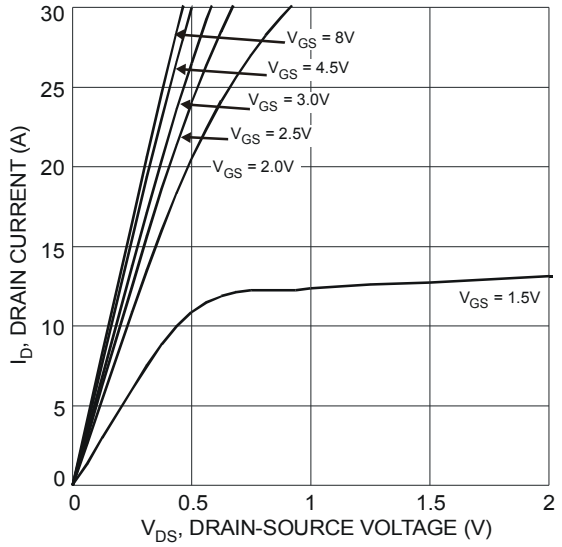


Fig. 1 Typical Output Characteristic

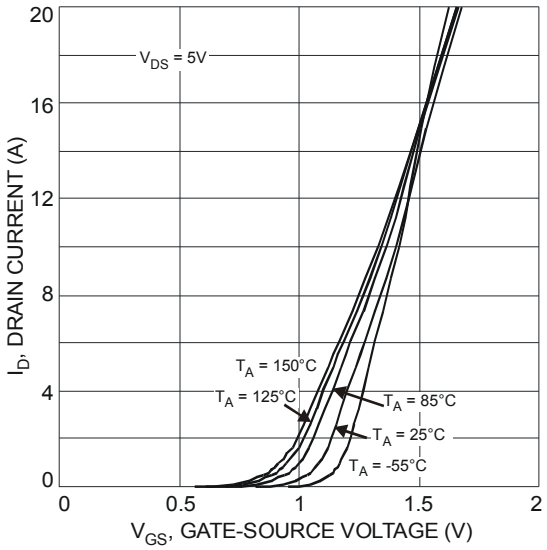


Fig. 2 Typical Transfer Characteristic

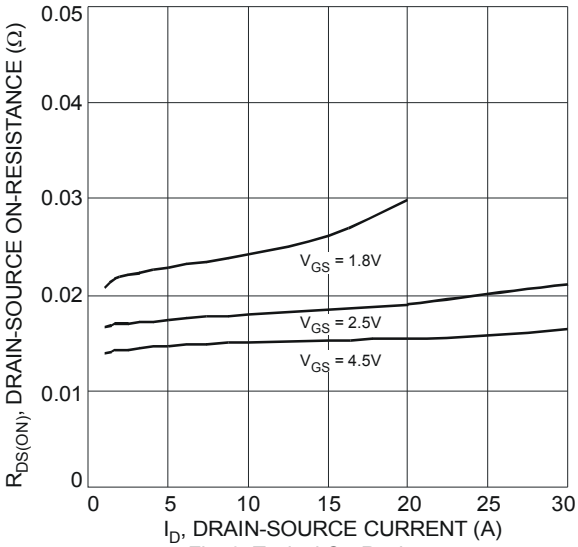


Fig. 3 Typical On-Resistance
vs. Drain Current and Gate Voltage

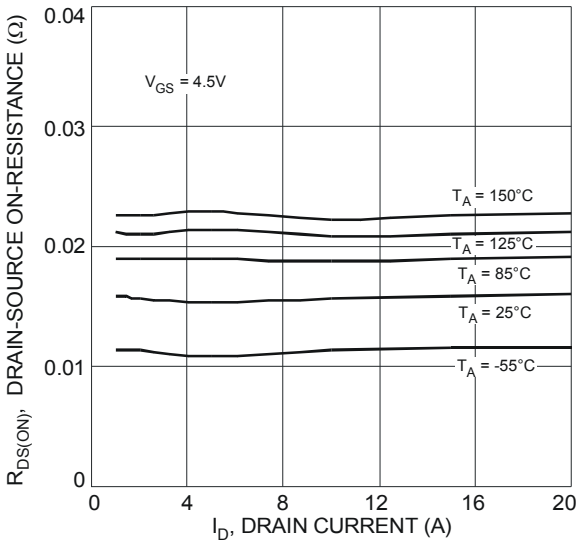


Fig. 4 Typical On-Resistance
vs. Drain Current and Temperature

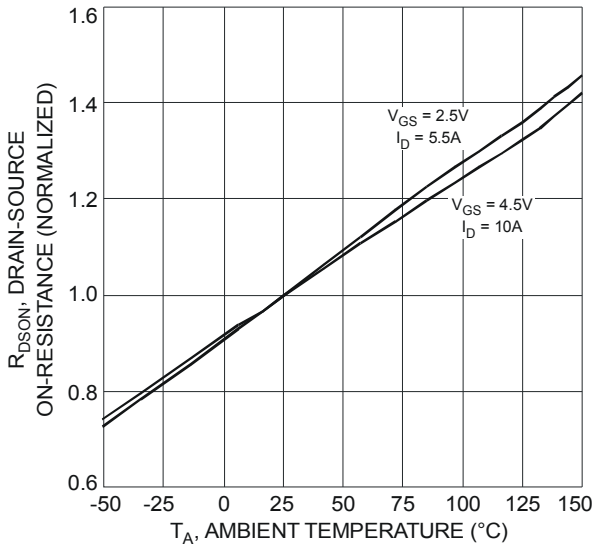


Fig. 5 On-Resistance Variation with Temperature

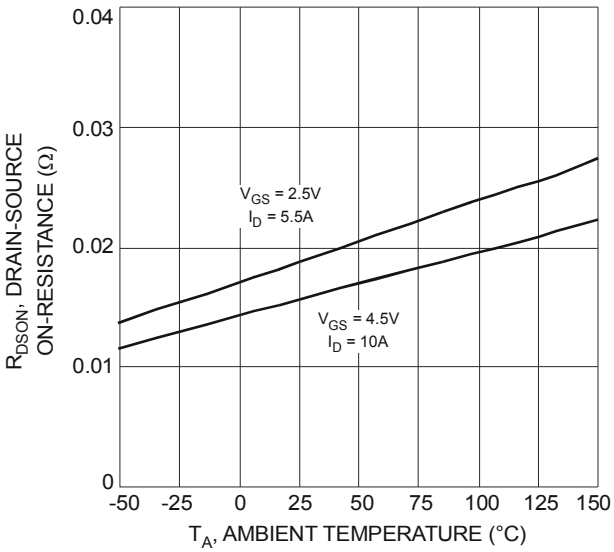


Fig. 6 On-Resistance Variation with Temperature

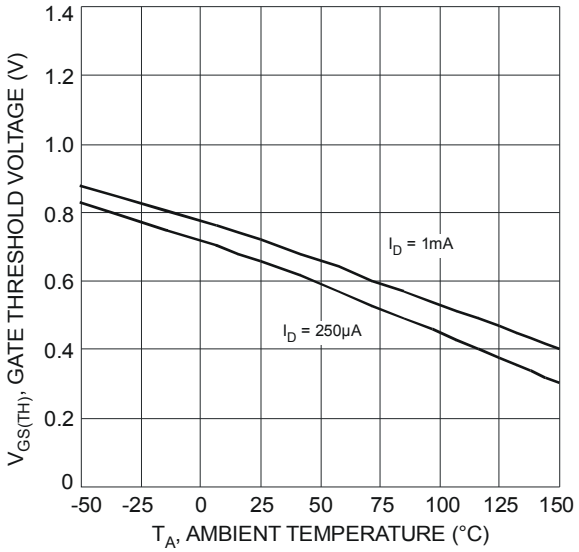


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

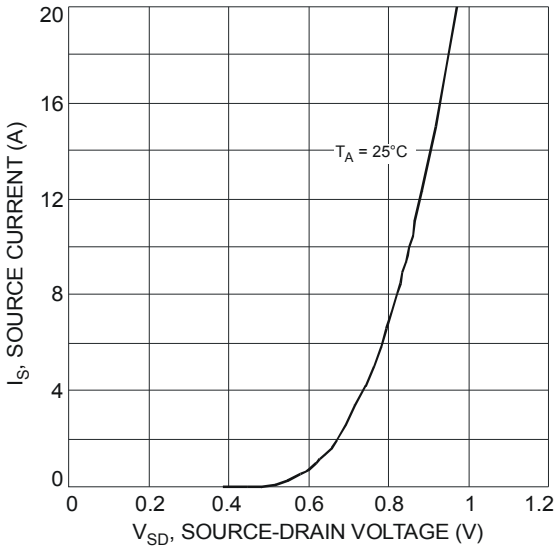


Fig. 8 Diode Forward Voltage vs. Current

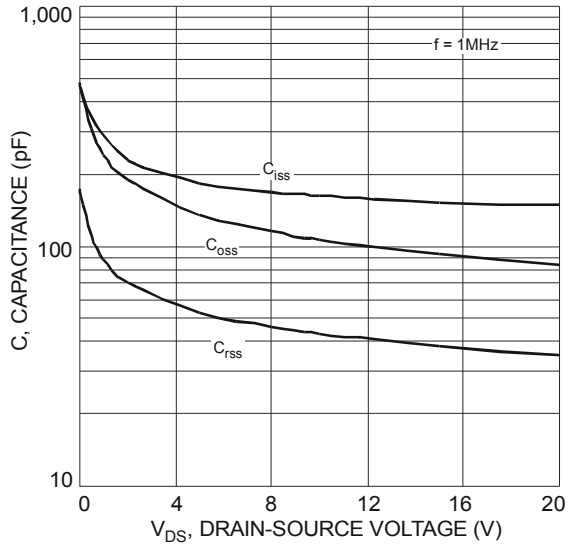


Fig. 9 Typical Total Capacitance

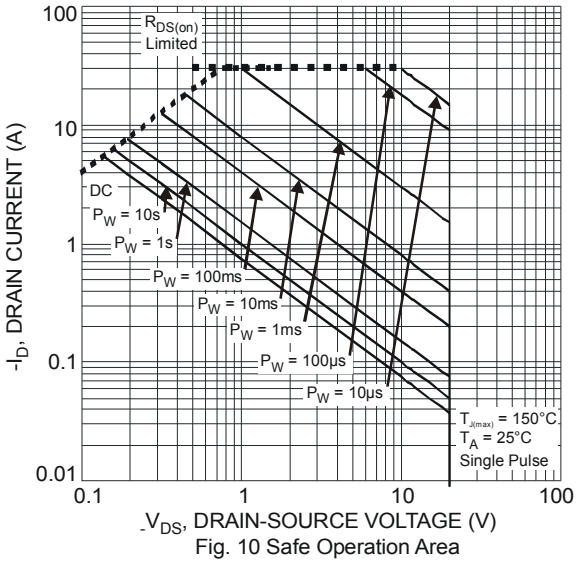


Fig. 10 Safe Operation Area

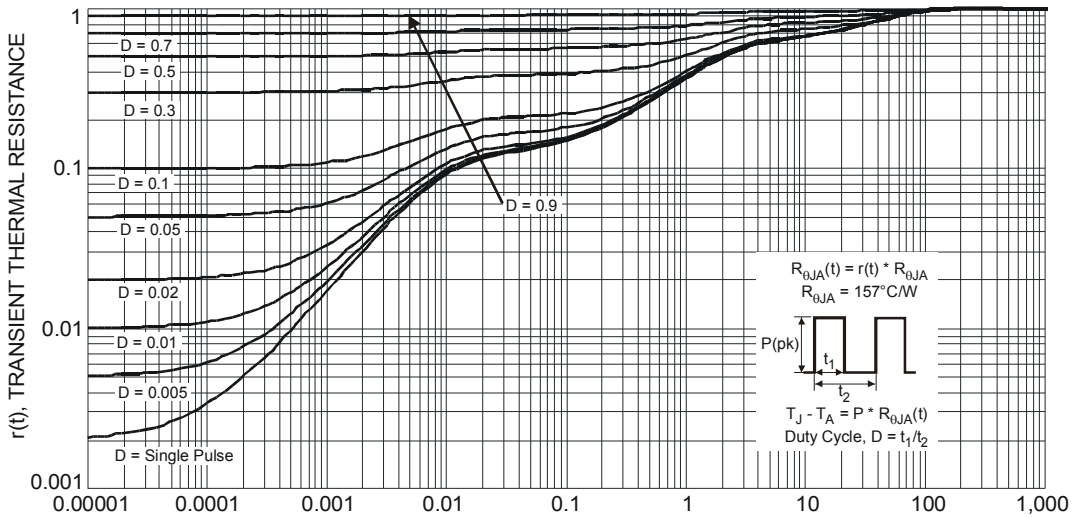
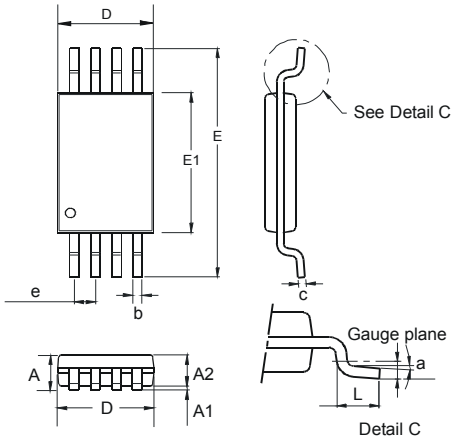


Fig. 11 Transient Thermal Response

Package Outline Dimensions

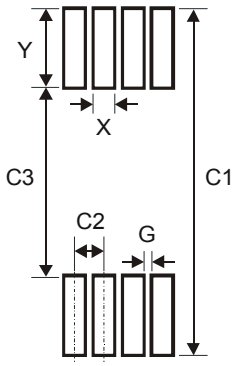
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TSSOP-8			
Dim	**Min**	**Max**	**Typ**
a	0.09	–	–
A	–	1.20	–
A1	0.05	0.15	–
A2	0.825	1.025	0.925
b	0.19	0.30	–
c	0.09	0.20	–
D	2.90	3.10	3.025
e	—	—	0.65
E	—	—	6.40
E1	4.30	4.50	4.425
L	0.45	0.75	0.60
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
X	0.45
Y	1.78
C1	7.72
C2	0.65
C3	4.16
G	0.20

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